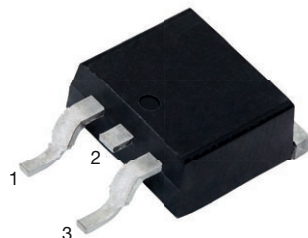
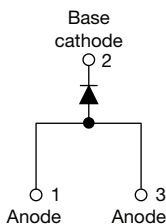


## High Voltage Surface Mount Input Rectifier Diode, 20 A


D<sup>2</sup>PAK (TO-263AB)


### FEATURES

- Glass passivated pellet chip junction
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### APPLICATIONS

- Input rectification
- Vishay Semiconductors switches and output rectifiers which are available in identical package outlines

### DESCRIPTION

The VS-20ETS...S-M3 rectifier High Voltage Series has been optimized for very low forward voltage drop, with moderate leakage. The glass passivation technology used has reliable operation up to 150 °C junction temperature.

### PRIMARY CHARACTERISTICS

$I_{F(AV)}$	20 A
$V_R$	800 V, 1200 V
$V_F$ at $I_F$	1.1 V
$I_{FSM}$	300 A
$T_J$ max.	150 °C
Package	D <sup>2</sup> PAK (TO-263AB)
Circuit configuration	Single

### OUTPUT CURRENT IN TYPICAL APPLICATIONS

APPLICATIONS	SINGLE-PHASE BRIDGE	THREE-PHASE BRIDGE	UNITS
Capacitive input filter $T_A = 55$ °C, $T_J = 125$ °C common heatsink of 1 °C/W	16.3	21	A

### MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{F(AV)}$	Sinusoidal waveform	20	A
$V_{RRM}$		800/1200	V
$I_{FSM}$		300	A
$V_F$	20 A, $T_J = 25$ °C	1.1	V
$T_J$		-40 to +150	°C

### VOLTAGE RATINGS

PART NUMBER	$V_{RRM}$ , MAXIMUM PEAK REVERSE VOLTAGE V	$V_{RSM}$ , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	$I_{RRM}$ AT 150 °C mA
VS-20ETS08S-M3	800	900	1
VS-20ETS12S-M3	1200	1300	

### ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current	$I_{F(AV)}$	$T_C = 105$ °C, 180° conduction half sine wave	20	A
Maximum peak one cycle non-repetitive surge current	$I_{FSM}$	10 ms sine pulse, rated $V_{RRM}$ applied	250	
		10 ms sine pulse, no voltage reapplied	300	
Maximum $I^2t$ for fusing	$I^2t$	10 ms sine pulse, rated $V_{RRM}$ applied	316	A <sup>2</sup> s
		10 ms sine pulse, no voltage reapplied	442	
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	$t = 0.1$ ms to 10 ms, no voltage reapplied	4420	A <sup>2</sup> √s

**ELECTRICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum forward voltage drop	$V_{FM}$	20 A, $T_J = 25\text{ }^{\circ}\text{C}$	1.1	V
Forward slope resistance	$r_t$	$T_J = 150\text{ }^{\circ}\text{C}$	10.4	$\text{m}\Omega$
Threshold voltage	$V_{F(TO)}$		0.85	V
Maximum reverse leakage current	$I_{RM}$	$T_J = 25\text{ }^{\circ}\text{C}$	0.1	mA
		$T_J = 150\text{ }^{\circ}\text{C}$	1.0	

**THERMAL - MECHANICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	$T_J, T_{Stg}$		-40 to +150	$^{\circ}\text{C}$
Maximum thermal resistance, junction to case	$R_{thJC}$	DC operation	1.3	$^{\circ}\text{C}/\text{W}$
Maximum thermal resistance, junction to ambient	$R_{thJA}^{(1)}$	For D <sup>2</sup> PAK version	62	
Typical thermal resistance, case to heatsink	$R_{thCS}$	Mounting surface, smooth, and greased	0.5	
Approximate weight			2	g
			0.07	oz.
Mounting torque	minimum		6.0 (5.0)	$\text{kgf} \cdot \text{cm}$
	maximum		12 (10)	$(\text{lbf} \cdot \text{in})$
Marking device		Case style D <sup>2</sup> PAK (TO-263AB)	20ETS08S	
			20ETS12S	

**Note**

- (1) When mounted on 1" square (650 mm<sup>2</sup>) PCB of FR-4 or G-10 material 4 oz. (140  $\mu\text{m}$ ) copper 40  $^{\circ}\text{C}/\text{W}$   
For recommended footprint and soldering techniques refer to application note #AN-994

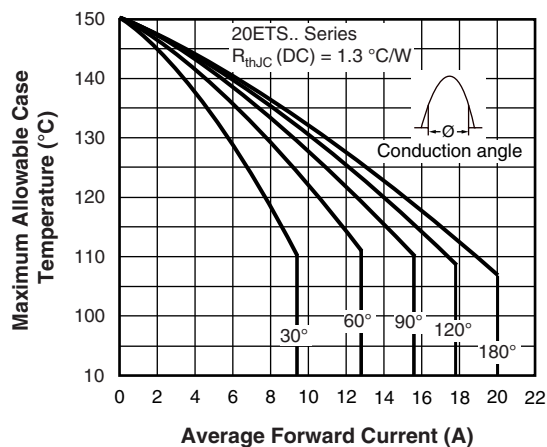


Fig. 1 - Current Rating Characteristics

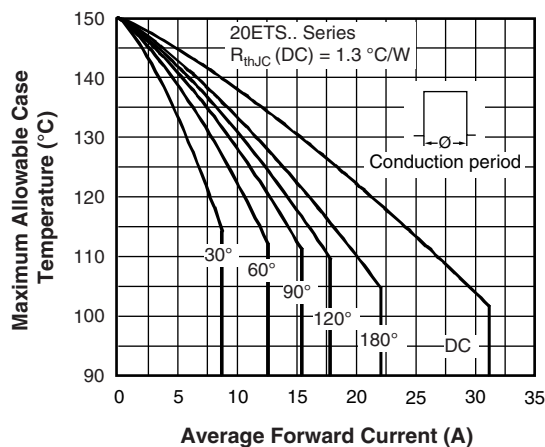


Fig. 2 - Current Rating Characteristics

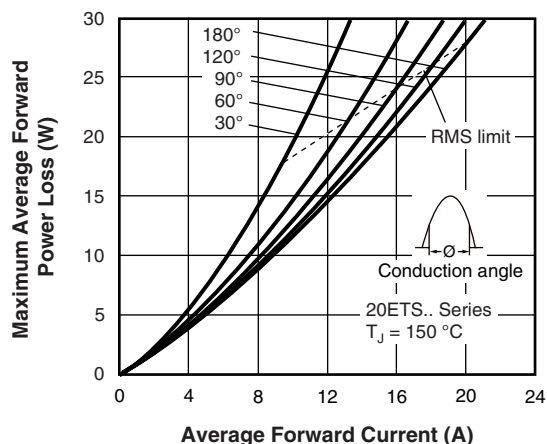


Fig. 3 - Forward Power Loss Characteristics

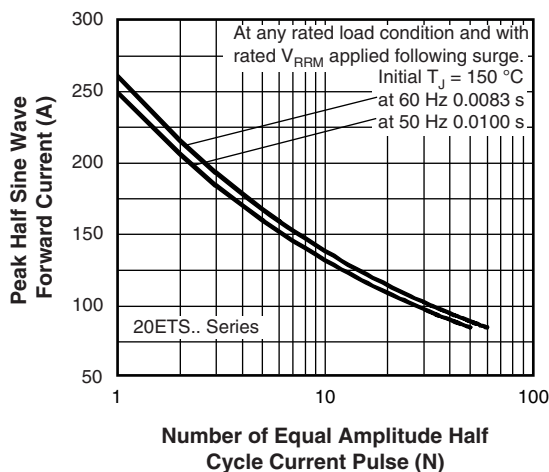


Fig. 5 - Maximum Non-Repetitive Surge Current

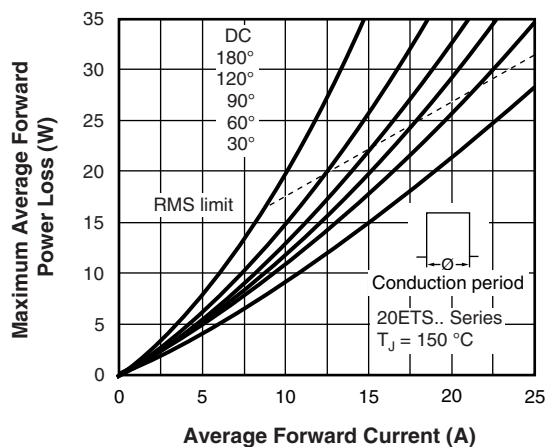


Fig. 4 - Forward Power Loss Characteristics

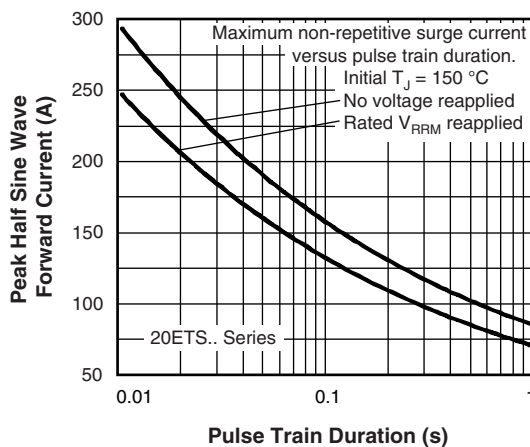


Fig. 6 - Maximum Non-Repetitive Surge Current

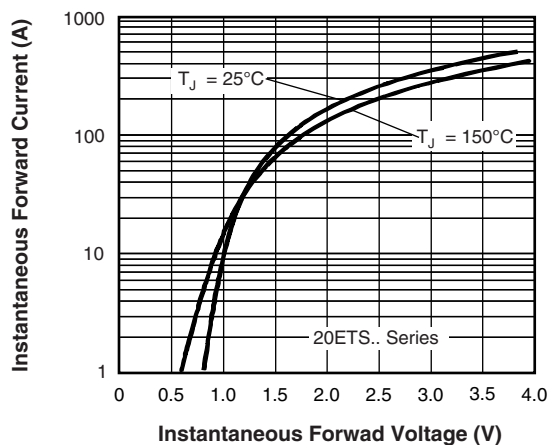


Fig. 7 - Forward Voltage Drop Characteristics

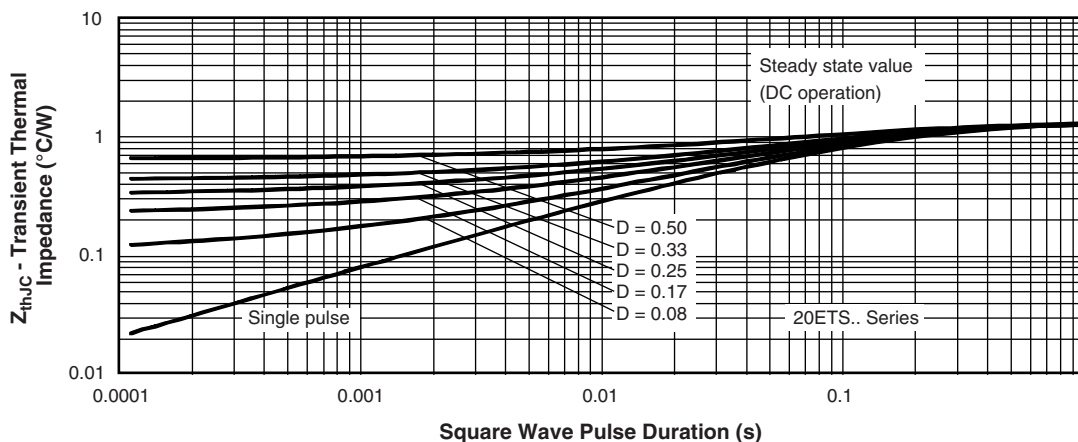


Fig. 8 - Thermal Impedance  $Z_{thJC}$  Characteristics

## ORDERING INFORMATION TABLE

Device code	VS-	20	E	T	S	12	S	TRL	-M3
	1	2	3	4	5	6	7	8	9

- 1** - Vishay Semiconductors product
- 2** - Current rating (20 = 20 A)
- 3** - Circuit configuration  
E = single
- 4** - Package:  
T = D<sup>2</sup>PAK (TO-263AB)
- 5** - Type of silicon:  
S = standard recovery rectifier
- 6** - Voltage code x 100 =  $V_{RRM}$  08 = 800 V  
12 = 1200 V
- 7** - S = surface mountable
- 8** - • None = tube  
• TRL = tape and reel (left oriented)  
• TRR = tape and reel (right oriented)
- 9** - -M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free



<b>ORDERING INFORMATION</b> (Example)		
<b>PREFERRED P/N</b>	<b>BASE QUANTITY</b>	<b>PACKAGING DESCRIPTION</b>
VS-20ETS08S-M3	50	Antistatic plastic tube
VS-20ETS08STRR-M3	800	13" diameter reel
VS-20ETS08STRL-M3	800	13" diameter reel
VS-20ETS12S-M3	50	Antistatic plastic tube
VS-20ETS12STRR-M3	800	13" diameter reel
VS-20ETS12STRL-M3	800	13" diameter reel

<b>LINKS TO RELATED DOCUMENTS</b>	
Dimensions	<a href="http://www.vishay.com/doc?96164">www.vishay.com/doc?96164</a>
Part marking information	<a href="http://www.vishay.com/doc?95444">www.vishay.com/doc?95444</a>
Packaging information	<a href="http://www.vishay.com/doc?96424">www.vishay.com/doc?96424</a>
SPICE model	<a href="http://www.vishay.com/doc?97266">www.vishay.com/doc?97266</a>

**D<sup>2</sup>PAK****DIMENSIONS** in millimeters and inchesConforms to JEDEC® outline D<sup>2</sup>PAK (SMD-220)

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
H	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010 BSC		
L4	4.78	5.28	0.188	0.208	

**Notes**

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inches
- (7) Outline conforms to JEDEC® outline TO-263AB



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